

# Lecture 6: Chipkill, PCM

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- Topics: error correction, PCM basics, PCM writes and errors

# Chipkill

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- Chipkill correct systems can withstand failure of an entire DRAM chip
- For chipkill correctness
  - the 72-bit word must be spread across 72 DRAM chips
  - or, a 13-bit word (8-bit data and 5-bit ECC) must be spread across 13 DRAM chips

# RAID-like DRAM Designs

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- DRAM chips do not have built-in error detection
- Can employ a 9-chip rank with ECC to detect and recover from a single error; in case of a multi-bit error, rely on a second tier of error correction
- Can do parity across DIMMs (needs an extra DIMM); use ECC within a DIMM to recover from 1-bit errors; use parity across DIMMs to recover from multi-bit errors in 1 DIMM
- Reads are cheap (must only access 1 DIMM); writes are expensive (must read and write 2 DIMMs)

Used in some HP servers

- Add a checksum to every row in DRAM; verified at the memory controller
- Adds area overhead, but provides self-contained error detection
- When a chip fails, can re-construct data by examining another parity DRAM chip
- Can control overheads by having checksum for a large row or one parity chip for many data chips
- Writes are again problematic

# SSC-DSD

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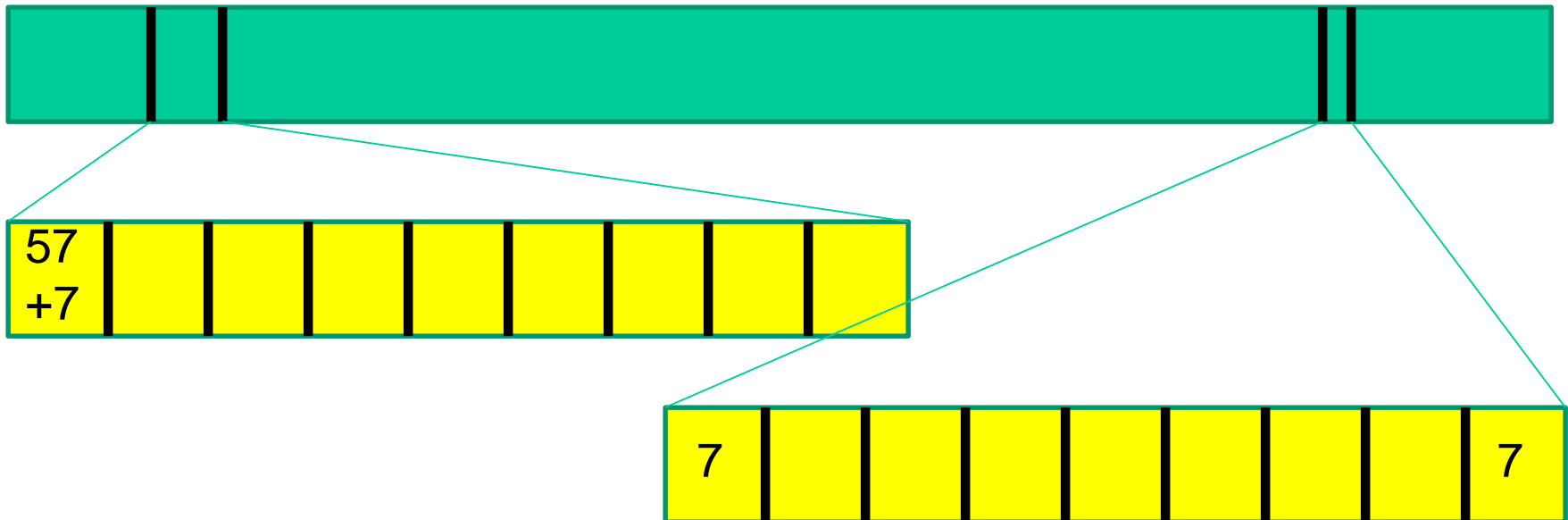
- The cache line is organized into multi-bit symbols
- Two symbols are required for error detection and 3/4 symbols are used for error correction (can handle complete failure in one symbol, i.e., each symbol is fetched from a different DRAM chip)
- 3-symbol codes are not popular because it leads to non-standard DIMMs
- 4-symbol codes are more popular, but are used as 32+4 so that standard ECC DIMMs can be used (high activation energy and low rank-level parallelism) (16+4 would require a non-standard DIMM)

- Also builds a two-tier error protection scheme, but does the second tier in software
- The second-tier codes are stored in the regular physical address space (not specialized DRAM chips); software has flexibility in terms of the types of codes to use and the types of pages that are protected
- Reads are cheap; writes are expensive as usual; but, the second-tier codes can now be cached; greatly helps reduce the number of DRAM writes
- Requires a 144-bit datapath (increases overfetch)

# LoT-ECC

Udipi et al., ISCA 2012

- Use checksums to detect errors and parity codes to fix
- Requires access of only 9 DRAM chips per read, but the storage overhead grows to 26%



# Phase Change Memory

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- Emerging NVM technology that can replace Flash and DRAM; there are other competing technologies too
- Much higher density; much better scalability; can do multi-level cells
- When materials (GST) are heated (with electrical pulses) and then cooled, they form either crystalline or amorphous materials depending on the intensity and duration of the pulses; crystalline materials have low resistance (1 state) and amorphous materials have high resistance (0 state)
- Non-volatile, fast reads ( $\sim 50\text{ns}$ ), slow and energy-hungry writes; limited lifetime ( $\sim 10^8$  writes per cell), no leakage

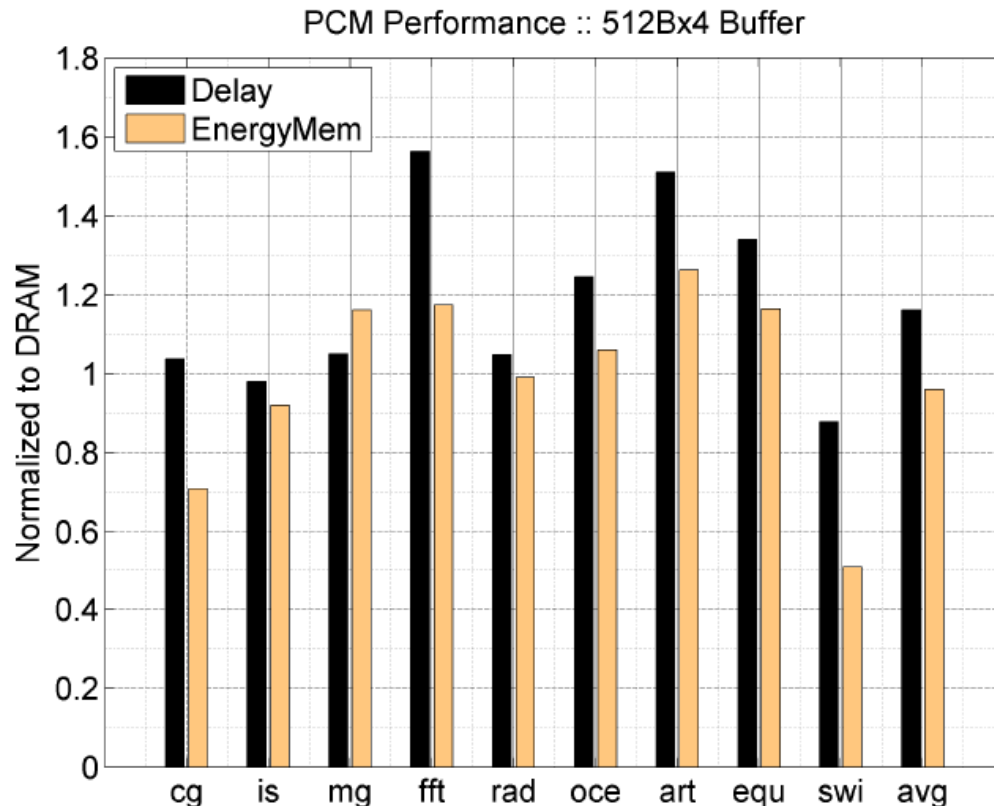


# PCM as a Main Memory

Lee et al., ISCA 2009

	PCM	DRAM
<b>Delay &amp; Timing</b>		
tRCD (cy)	22	5
tCL (cy)	5	5
tWL (cy)	4	4
tCCD (cy)	4	4
tWTR (cy)	3	3
tWR (cy)	6	6
tRTP (cy)	3	3
tRP (cy)	60	5
tRRDact (cy)	2	3
tRRDpre (cy)	11	3
<b>Energy</b>		
Array read (pJ/bit)	2.47	1.17
Array write (pJ/bit)	16.82	0.39
Buffer read (pJ/bit)	0.93	0.93
Buffer write (pJ/bit)	1.02	1.02
Background power (pJ/bit)	0.08	0.08

- Two main innovations to overcome these drawbacks:
  - decoupled row buffers and non-destructive PCM reads
  - multiple narrow row buffers (row buffer cache)



# Optimizations for Writes (Energy, Lifetime)

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- Read a line before writing and only write the modified bits  
Zhou et al., ISCA'09
- Write either the line or its inverted version, whichever causes fewer bit-flips  
Cho and Lee, MICRO'09
- Only write dirty lines in a PCM page (when a page is evicted from a DRAM cache)  
Lee et al., Qureshi et al., ISCA'09
- When a page is brought from disk, place it only in DRAM cache and place in PCM upon eviction  
Qureshi et al., ISCA'09
- Wear-leveling: rotate every new page, shift a row periodically, swap segments  
Zhou et al., Qureshi et al., ISCA'09

# Hard Error Tolerance in PCM

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- PCM cells will eventually fail; important to cause gradual capacity degradation when this happens
- Pairing: among the pool of faulty pages, pair two pages that have faults in different locations; replicate data across the two pages  
Ipek et al., ASPLOS'10
- Errors are detected with parity bits; replica reads are issued if the initial read is faulty

- Instead of using ECC to handle a few transient faults in DRAM, use error-correcting pointers to handle hard errors in specific locations
- For a 512-bit line with 1 failed bit, maintain a 9-bit field to track the failed location and another bit to store the value in that location
- Can store multiple such pointers and can recover from faults in the pointers too
- ECC has similar storage overhead and can handle soft errors; but ECC has high entropy and can hasten wearout

- Most PCM hard errors are stuck-at faults (stuck at 0 or stuck at 1)
- Either write the word or its flipped version so that the failed bit is made to store the stuck-at value
- For multi-bit errors, the line can be partitioned such that each partition has a single error
- Errors are detected by verifying a write; recently failed bit locations are cached so multiple writes can be avoided

- When a PCM block (64B) is unusable because the number of hard errors has exceeded the ECC capability, it is remapped to another address; the pointer to this address is stored in the failed block; need another bit per block
- The pointer can be replicated many times in the failed block to tolerate the multiple errors in the failed block
- Requires two accesses when handling failed blocks; this overhead can be reduced by caching the pointer at the memory controller

# Title

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